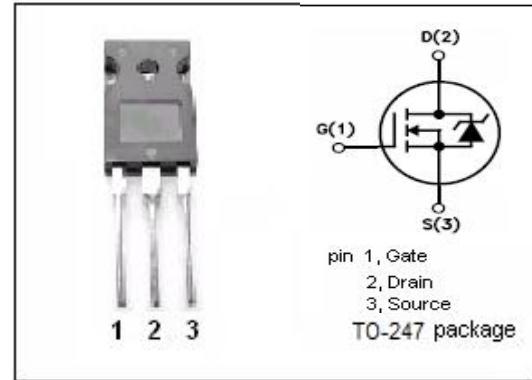


## Isc N-Channel MOSFET Transistor

**FDH45N50F**

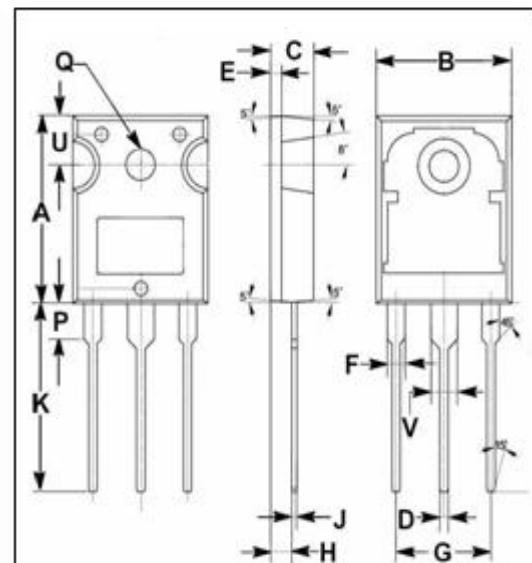
### • FEATURES

- With TO-247 package
- Low input capacitance and gate charge
- Low gate input resistance
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation



### • APPLICATIONS

- Switching applications



### • ABSOLUTE MAXIMUM RATINGS( $T_a=25^\circ\text{C}$ )

| SYMBOL    | PARAMETER  | VALUE      | UNIT             |
|-----------|--|------------|------------------|
| $V_{DSS}$ | Drain-Source Voltage   | 500        | V                |
| $V_{GSS}$ | Gate-Source Voltage  | $\pm 30$   | V                |
| $I_D$     | Drain Current-Continuous @ $T_c=25^\circ\text{C}$<br>$T_c=100^\circ\text{C}$ | 45<br>28.4 | A                |
| $I_{DM}$  | Drain Current-Single Pulsed  | 180        | A                |
| $P_D$     | Total Dissipation @ $T_c=25^\circ\text{C}$                                   | 625        | W                |
| $T_{ch}$  | Max. Operating Junction Temperature  | 150        | $^\circ\text{C}$ |
| $T_{stg}$ | Storage Temperature  | -55~150    | $^\circ\text{C}$ |

### • THERMAL CHARACTERISTICS

| SYMBOL         | PARAMETER                             | MAX | UNIT                      |
|----------------|---------------------------------------|-----|---------------------------|
| $R_{th(ch-c)}$ | Channel-to-case thermal resistance    | 0.2 | $^\circ\text{C}/\text{W}$ |
| $R_{th(ch-a)}$ | Channel-to-ambient thermal resistance | 40  | $^\circ\text{C}/\text{W}$ |

| DIM | mm    |       |
|-----|-------|-------|
|     | MIN   | MAX   |
| A   | 19.80 | 20.20 |
| B   | 15.40 | 15.80 |
| C   | 4.90  | 5.10  |
| D   | 0.90  | 1.10  |
| E   | 1.40  | 1.60  |
| F   | 1.90  | 2.10  |
| G   | 10.80 | 11.00 |
| H   | 2.40  | 2.60  |
| J   | 0.50  | 0.70  |
| K   | 19.50 | 20.50 |
| P   | 3.90  | 4.10  |
| Q   | 3.30  | 3.50  |
| U   | 5.20  | 5.40  |
| V   | 2.90  | 3.10  |

**Isc N-Channel MOSFET Transistor****FDH45N50F****ELECTRICAL CHARACTERISTICS** $T_c=25^\circ\text{C}$  unless otherwise specified

| SYMBOL                     | PARAMETER                      | CONDITIONS  | MIN | TYP | MAX       | UNIT             |
|----------------------------|--------------------------------|---|-----|-----|-----------|------------------|
| $\text{BV}_{\text{DSS}}$   | Drain-Source Breakdown Voltage | $\text{V}_{\text{GS}}=0\text{V}; \text{I}_D=0.25\text{mA}$  | 500 |     |           | V                |
| $\text{V}_{\text{GS(th)}}$ | Gate Threshold Voltage         | $\text{V}_{\text{DS}}= \pm 30\text{V}; \text{I}_D=0.25\text{mA}$  | 3.0 |     | 5.0       | V                |
| $\text{R}_{\text{DS(on)}}$ | Drain-Source On-Resistance     | $\text{V}_{\text{GS}}= 10\text{V}; \text{I}_D=22.5\text{A}$   |     | 105 | 120       | $\text{m}\Omega$ |
| $\text{I}_{\text{GSS}}$    | Gate-Source Leakage Current    | $\text{V}_{\text{GS}}= \pm 30\text{V}; \text{V}_{\text{DS}}= 0\text{V}$   |     |     | $\pm 0.1$ | $\mu\text{A}$    |
| $\text{I}_{\text{DSS}}$    | Drain-Source Leakage Current   | $\text{V}_{\text{DS}}= 500\text{V}; \text{V}_{\text{GS}}= 0\text{V}; \text{T}_j=25^\circ\text{C}$<br>$\text{V}_{\text{DS}}= 400\text{V}; \text{V}_{\text{GS}}= 0\text{V}; \text{T}_j=125^\circ\text{C}$ |     |     | 25<br>250 | $\mu\text{A}$    |
| $\text{V}_{\text{SDF}}$    | Diode forward voltage          | $\text{I}_{\text{SD}}=45\text{A}, \text{V}_{\text{GS}} = 0 \text{ V}$   |     |     | 1.4       | V                |